

SZMM5Zx-Q1 Zener Voltage Regulator Diode in SOD-523

1 Features

- Low I/O capacitance
 - 75pF (max)
- Low leakage current
 - <500nA (max)
- AEC-Q101 qualified
- Temperature range: –55°C to +150°C
- Leaded package used for automatic optical inspection (AOI)

2 Applications

- Voltage regulation
- Over-voltage protection

3 Description

The SZMM5Zx-Q1 is a single channel Zener diode in a SOD-523 package.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾
SZMM5Zx-Q1	DYA (SOD-523, 2)	1.60mm × 0.80mm

- (1) For more information, see [Section 9](#).
 (2) The package size (length × width) is a nominal value and includes pins, where applicable.

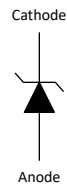


Figure 3-1. Functional Block Diagram



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ADVANCE INFORMATION

4 Pin Configuration and Functions

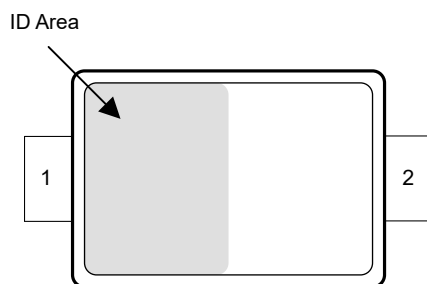


Figure 4-1. DYA Package, 2-Pin SOD-523 (Top View)

Table 4-1. Pin Functions

PIN		DESCRIPTION
NAME	NO.	
C	1	Cathode
A	2	Anode

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		MIN	MAX	UNIT
T _A	Ambient Operating Temperature	-55	150	°C
T _{stg}	Storage Temperature	-65	155	°C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute maximum ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If briefly operating outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.

5.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
V _f	Forward Voltage	I _F = 10mA			0.9	V
T _A	Operating free-air temperature		-55		150	°C

5.3 Electrical Characteristics_8.2v

At T_A=25°C (unless otherwise noted) ⁽¹⁾

PARAMETER			TEST CONDITION		MIN	TYP	MAX	UNIT
V _Z	Zener Voltage	@I _{ZT} 5mA			7.79	8.2	8.61	V
Z _{zT}	Zener Impedance	@I _{ZT} 5mA				2	10	Ω
I _R	Leakage Current	I _R @ V _R 5.75v					500	nA
Θ _{VZ}	Temp Coeff.	@I _{ZT} 5mA			3.2		6.2	mV/C
CD	Diode capacitance	V _R =0, f=1MHz					75	pF

- (1) Typical parameters are measured at 25°C

6 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

6.1 Application Information

The SZMM5Zx-Q1 is a single channel Zener diode that can be used for applications such as voltage regulation and over-voltage protection.

7 Device and Documentation Support

7.1 Documentation Support

7.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

7.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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7.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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7.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

7.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

8 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
November 2024	*	Initial Release

9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
PZMM5Z8V2DYARQ1	Active	Preproduction	SOT-5X3 (DYA) 2	3000 LARGE T&R	-	Call TI	Call TI	-55 to 150	
PZMM5Z8V2DYARQ1.B	Active	Preproduction	SOT-5X3 (DYA) 2	3000 LARGE T&R	-	Call TI	Call TI	-55 to 150	

- (1) **Status:** For more details on status, see our [product life cycle](#).
- (2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- (3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- (4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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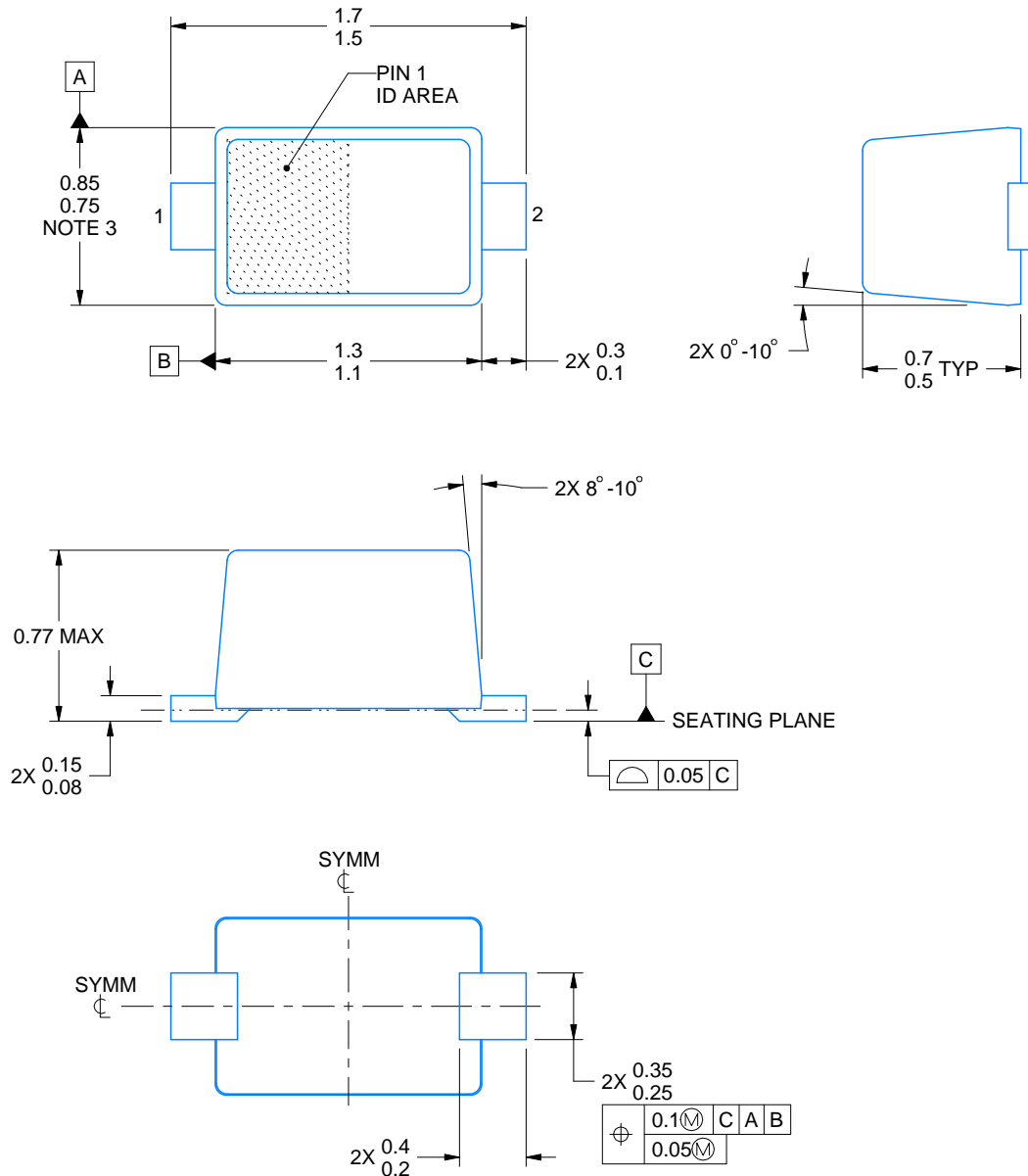
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DYA0002A

PACKAGE OUTLINE

SOT (SOD-523) - 0.77 mm max height

PLASTIC SMALL OUTLINE



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NOTES:

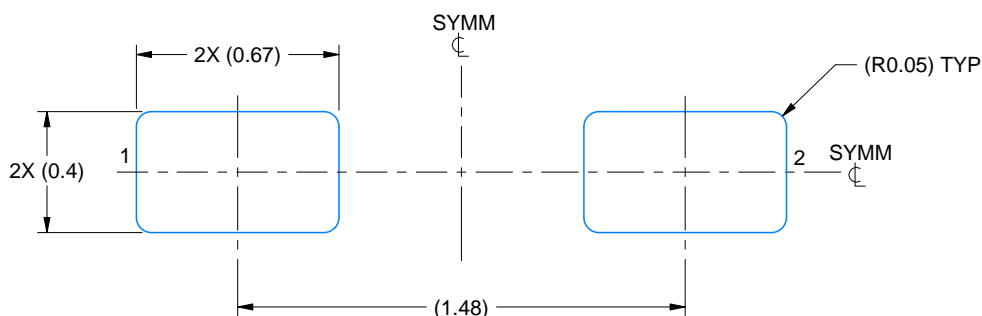
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEITA SC-79 registration except for package height

EXAMPLE BOARD LAYOUT

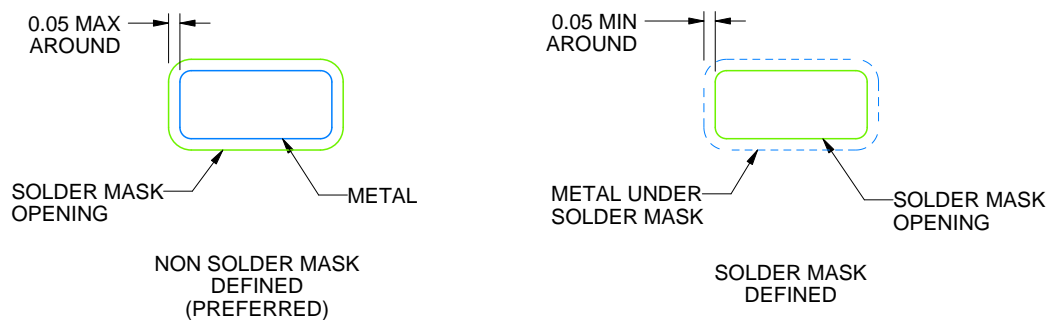
DYA0002A

SOT (SOD-523) - 0.77 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
SCALE:40X



SOLDERMASK DETAILS

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NOTES: (continued)

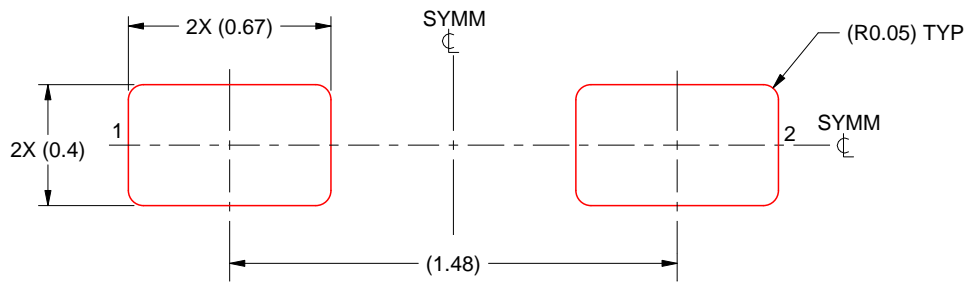
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DYA0002A

SOT (SOD-523) - 0.77 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:40X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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